

The PA-150AAD-C is designed to meet requirements of pilot lines and mass production lines of "MEMS Wafer", "Opt-devices", "Communication Devices", "DNA chips", and "Bump", process as well.

The system enables high resolution exposure, because the system has an auto-alignment function for both top and back surface of wafer, and has three modes in exposure process, proximity, hard contact and soft contact mode.



Specifications	Descriptions
Wafer Size	4, 5, 6 inch (Si, GaAs, Ceramic and etc.)
Mask Size	5, 6, 7 inch
Exposure Mode	Proximity, Hard Contact, Soft Contact
Exposure Gap	0 - 100 μm (Resolution: 1 μm)
Resolution	L/S 1 μm at Hard Contact
Light Source	UV Lamp 500W, 20 mW/cm ²
Light Distribution	More than 90% (\pm 5%)
Light Collimation Angle	\leq 1.0° (Half Angle)
Light Declination Angle	\leq 1.5°
Alignment Accuracy	Top Surface \pm 1 μm , Back Surface \pm 2 μm
Objective Lens	Top Side: 5X or 10X or 20X Back Side: 10X (Fixed)
Stage	X, Y, Z, θ Stage (AC Servo Driven)
Camera Unit	1/2 inch CCD Camera (4 Sets)
Dimensions	Approx. 1,500 (W) x 1,300 (D) x 1,667 (H)mm
Weight	Approx. 1,500 Kg

Features

- High accuracy alignment for both top and back surface by a high resolution objective lens
- High accuracy paralleling mechanism (Wafer to Mask)
- Precise pressure control for the mask contact
- Auto wafer transportation and auto alignment
- Precise gap control by laser beam sensor (Gas sensing and feedback)

Options

The following models are available:

PA-150MAD: Manual alignment system

PA-150AADC: Auto alignment and cassette to cassette wafer transportation system

Utilities

Line Power: AC200V, 3 Phase, 15A

Vacuum: 600mm Hg (1/4 inch, Female)

Compressed air: 0.4 Mpa, 50 litre/nl (1/4 inch, Female, Swagelock)